

Bill of Materials

TI DESIGNS

TIDA-00514

Item	Qty	Reference	Value	Part Description	Manufacturer	Manufacturer Part Number	PCB Footprint
1	1	!PCB		Printed Circuit Board	Any	TIDA-00514	
2	6	C11, C15, C41, C43, C49,	1uF	CAP, CERM, 1 µF, 16 V, +/- 10%, X5R, 0603	TDK	C1608X5R1C105K	0603
3	2	C13, C14	0.01uF	CAP, CERM, 0.01 µF, 50 V, +/- 5%, X7R, 0603	Kemet	C0603C103J5RACTU	0603
4	3	C16, C50, C54	10uF	CAP, CERM, 10 µF, 16 V, +/- 10%, X6S, 0805	TDK	C2012X6S1C106MT	0805
5	1	C45	0.33uF	CAP, CERM, 0.33 µF, 16 V, +/- 10%, X7R, 0603	Kemet	C0603C334K4RACTU	0603
6	4	H9, H10, H11, H12		Bumpon, Hemisphere, 0.44 X 0.20, Clear	3M	SJ-5303 (CLEAR)	Transparent Bumpon
7	6	J11, J12, J41, J42, J43, J44		TERMINAL BLOCK 5.08MM VERT 2POS, TH	On-Shore Technology	ED120/2DS	TERM_BLK, 2pos, 5.08mm
8	4	JP11, JP41, JP42, JP44		Header, 100mil, 3x1, Gold, TH	Samtec	TSW-103-07-G-S	3x1 Header
9	2	JP12, JP43		Header, 100mil, 2x1, Gold, TH	Samtec	HMTSW-102-07-G-S-240	Header, 2.54mm, 2x1, TH
10	2	Q41, Q42	12V	MOSFET, N/P-CH, 12 V, 2.1 A, 1.0x0.35x0.6mm	Texas Instruments	CSD13381F4	1.0x0.35x0.6mm
11	1	R42	10k	RES, 10 k, 5%, 0.1 W, 0603	Yageo America	RC0603JR-0710KL	0603
12	3	R43, R46, R49	100k	RES, 100 k, 1%, 0.1 W, 0603	Yageo America	RC0603FR-07100KL	0603
13	2	R44, R45	499k	RES, 499 k, 1%, 0.1 W, 0603	Yageo America	RC0603FR-07499KL	0603
14	1	R48	0.001	RES, 0.001, 1%, 1 W, 2512	Panasonic	ERJ-M1WTF1M0U	2512
15	9	SH-JP11, SH-JP12, SH-JP21, SH-JP22, SH-JP31, SH-JP32, SH-JP41, SH-JP42, SH-JP43	1x2	Shunt, 100mil, Gold plated, Black	3M	969102-0000-DA	Shunt
16	14	TP11, TP13, TP14, TP15, TP16, TP41, TP43, TP45, TP46, TP47, TP48, TP49, TP50, TP52	Red	Test Point, Compact, Red, TH	Keystone	5005	Red Compact Testpoint
17	13	TP12, TP17, TP18, TP19, TP42, TP44, TP51, TP53, TP54, TP55, TP56, TP57, TP58	Black	Test Point, Miniature, Black, TH	Keystone	5001	Black Miniature Testpoint
18	4	U11, U12, U41, U42		ULTRA-LOW RESISTANCE LOAD SWITCH, DNY0008A	Texas Instruments	TPS22959DNY	DNY0008A
19	0	C12, C17, C42, C44, C51, C55	10uF	CAP, CERM, 10 µF, 16 V, +/- 10%, X6S, 0805	TDK	C2012X6S1C106MT	0805
20	0	C18, C52, C56	47uF	CAP, CERM, 47 µF, 16 V, +/- 15%, X5R, 1206	TDK	C3216X5R1C476M160AB	1206
21	0	C46	0.33uF	CAP, CERM, 0.33 µF, 16 V, +/- 10%, X7R, 0603	Kemet	C0603C334K4RACTU	0603
22	0	C47, C48	0.01uF	CAP, CERM, 0.01 µF, 50 V, +/- 5%, X7R, 0603	Kemet	C0603C103J5RACTU	0603
23	0	FID1, FID2, FID3		Fiducial mark. There is nothing to buy or mount.	N/A	N/A	Fiducial
24	0	R41, R47	0.001	RES, 0.001, 1%, 1 W, 2512	Panasonic	ERJ-M1WTF1M0U	2512

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